



IFW
PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

February 22, 2010

Applicants: Katsuyuki TSUCHIDA et al

For: COPPER ELECTROLYTIC SOLUTION CONTAINING AS ADDITIVE
COMPOUND HAVING SPECIFIC SKELETON, AND ELECTROLYTIC
COPPER FOIL MANUFACTURED THEREWITH

Serial No.: 10/588 686 Group: 1795

Confirmation No.: 9917

Filed: August 7, 2006 Examiner: Wong

International Application No.: PCT/JP2005/022662

International Filing Date: December 9, 2005

Atty. Docket No.: 4700.P0335US

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO RESTRICTION REQUIREMENT

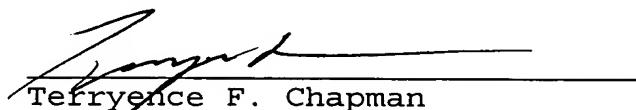
Sir:

In response to the Office Action dated January 27, 2010,
please amend the above-identified application as follows:

(Please see following pages.)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service with
sufficient postage as first class mail in an envelope
addressed to: Commissioner for Patents, P.O. Box 1450,
Alexandria, VA 22313-1450, on February 22, 2010.


Terryence F. Chapman